

## ABSTRACT

A window ball grid array (WBGA) semiconductor package and a method for fabricating the same are provided. The semiconductor package includes: a substrate having an upper surface and an opposite lower surface and having an opening penetrating through the same; at least one chip mounted on the upper surface and over the opening of the substrate via an adhesive, and electrically connected to the lower surface of the substrate via a plurality of bonding wires going through the opening; an encapsulation body formed on the upper and lower surfaces of the substrate for encapsulating the chip and the bonding wires and filling the opening of the substrate and gaps, not applied with the adhesive, between the chip and the substrate; and a plurality of solder balls bonded to area free of the encapsulation body on the lower surface of the substrate and exposed outside.

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